

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	26	('flip chip') near15 packag\$3 and substrate and ('first hole' 'second hole') and (bump or solder) and (filler or adhesive or resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/10/13 11:55
L2	1487	('flip chip') near15 packag\$3 and substrate and (first or second) near5 (bump or solder) and (filler or adhesive or resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/10/13 11:55